



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-09-14
Contact Name *	Refer to Supplier comment section	Contact Title	Refer to Supplier comment section
Authorized Representative *	Floriana San Biagio	Representative Title	AMG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	N7AB*MV7UABB	B	Z7GA	2017-09-14
Amount	UoM	Unit type	ST ECOPACK Grade	
13.2	mg	Each	ECOPACK® 2	
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant			

Manufacturing information			
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	
3	260	3	
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment
Not Applicable ; if coating is used c	Nickel/Gold (Ni/Au), electrolytic	Copper Alloy	



Package Designator	Size	Nbr of instances	Shape
LGA	2.5x 3x 0.86	14	No lead
Comment	Package: A08N VFLGA2.5X3X.86 14L P.5 L.475X.25; MDF valid for LSM6DSMTR-LSM6DSLTR		

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description
7c-I	Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices,

QueryList : REACH-7 July 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	N7AB*MV7UABB									
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Dies	Other inorganic materials	6.675	mg	supplier	die	Silicon (Si)	7440-21-3		6.205	mg	929588	470076				
				supplier	metallisation	Aluminium (Al)	7429-90-5		0.015	mg	2247	1136				
				supplier	metallisation	Copper (Cu)	7440-50-8		0.018	mg	2697	1364				
				supplier	metallisation	Cobalt (Co)	7440-48-4		0.013	mg	1948	985				
				supplier	metallisation	Tantalum (Ta)	7440-25-7		0.004	mg	599	303				
				supplier	metallisation	Titanium (Ti)	7440-32-6		0.006	mg	899	455				
				supplier	metallisation	Tungsten (W)	7440-33-7		0.002	mg	300	152				
				supplier	metallisation	Zirconium (Zr)	7440-67-7		0.002	mg	300	152				
				supplier	Passivation	Silicon Nitride (SiN)	12033-89-5		0.010	mg	1498	758				
				supplier	passivation	Silicon Oxide	7631-86-9		0.080	mg	11985	6061				
					JIG - R	die glass coating	Lead-Borate Glass	65997-18-4	7c-i-Electrical and electron	0.319	mg	47790	24167			
					supplier	UBM	Copper (Cu)	7440-50-8		0.001	mg	150	76			
				substrate	Other Organic Materials	2.824	mg	supplier	core material	Fiber glass	65997-17-3		0.396	mg	140227	30000
								supplier	core material	Bisphenol F type epoxy resin	9003-36-5		0.221	mg	78258	16742
								supplier	core material	Bismaleimide (B)	105391-33-1		0.134	mg	47450	10152
supplier	core material	Triazine (T)	25722-66-1						0.134	mg	47450	10152				
supplier	core material	metal hydroxide	21645-51-2						0.009	mg	3187	682				
supplier	core material	Zinc hydroxyde	20427-58-1						0.002	mg	708	152				
supplier	core material	Calcium sulfate	7778-18-9						0.005	mg	1771	379				
supplier	Solder mask	Acrylic resin	9003-01-4						0.155	mg	54887	11742				
supplier	Solder mask	Barium sulfate	7727-43-7						0.044	mg	15581	3333				
supplier	Solder mask	epoxy resin	85954-11-6						0.038	mg	13456	2879				
supplier	Solder mask	Talc containing no asbestiform fibers	14807-96-6						0.027	mg	9561	2045				
supplier	Solder mask	aromatic hydrocarbon	Proprietary						0.018	mg	6374	1364				
supplier	Solder mask	(2-methoxymethylethoxy)propanol	34590-94-8						0.009	mg	3187	682				
supplier	Solder mask	Quartz	14808-60-7						0.003	mg	1062	227				
supplier	Solder mask	amine compound	Proprietary						0.001	mg	354	76				
	supplier	metallisation	Copper (Cu)	7440-50-8		1.610	mg	570113	121970							
	Nickel (Ni)	metallisation	Nickel (Ni)	7440-02-0		0.016	mg	5666	1212							
	Precious metals	metallisation	Gold (Au)	7440-57-5		0.002	mg	708	152							
Die attach	Other Organic Materials	0.293	mg	supplier	tape	Acrylic resin	9003-01-4		0.088	mg	300341	6667				
				supplier	tape	epoxy resin	Proprietary		0.088	mg	300341	6667				
				supplier	tape	amorphous silica	7631-86-9		0.088	mg	300341	6667				
				supplier	tape	Polyester resin	Proprietary		0.029	mg	98976	2197				
Bonding wire	Precious metals	0.640	mg	supplier	wire	Gold (Au)	7440-57-5		0.634	mg	990625	48030				
				supplier	wire	Palladium (Pd)	7440-05-3		0.006	mg	9375	455				
encapsulation	Other Organic Materials	2.768	mg	supplier	mold compound	Silica, vitreous	60676-86-0		2.505	mg	904986	189773				
				supplier	mold compound	Epoxyde Bisphenol A Resin	25068-38-6		0.069	mg	24928	5227				
				supplier	mold compound	Epoxy Resin	29690-82-2		0.111	mg	40101	8409				
				supplier	mold compound	Phenol Resin	25068-38-6		0.069	mg	24928	5227				
				supplier	mold compound	Carbon black	1333-86-4		0.014	mg	5058	1061				